

Refining & Chemicals Polymers Technical data sheet Polypropylene – Metallocene Homopolymer Produced in Europe

## Description

Polypropylene Lumicene® MR 2002 is a metallocene polypropylene with a Melt Flow Index of 15 g/10 min.

Polypropylene Lumicene<sup>®</sup> MR 2002 is characterized by high fluidity for high speed spinning on spun laid nonwoven lines where spun filaments are produced to form a web that is then thermally bonded to manufacture products for hygienic and technical uses.

Polypropylene Lumicene® MR 2002 has a special anti gas-fading formulation to reduce yellowing in fibres.

## **Characteristics**

	Method	Unit	Typical Value
Rheological properties			
Melt Flow Index 230°C/2.16 kg	ISO 1133	g/10 min	15
Mechanical properties			
Flexural modulus	ISO 178	MPa	1300
Thermal properties			
Melting Point	ISO 3146	°C	151
Other physical properties			
Density	ISO 1183	g/cm <sup>3</sup>	0.905
Bulk Density	ISO 1183	g/cm <sup>3</sup>	0.525

## Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: <u>www.polymers.totalenergies.com</u>.

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